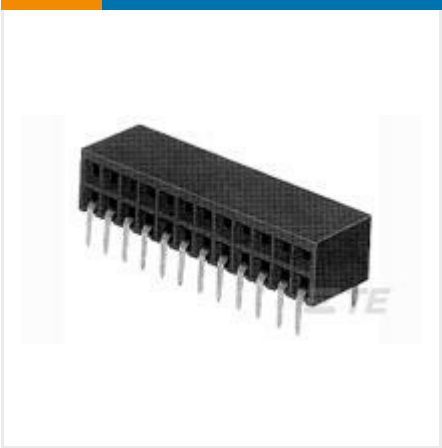




+ CONNECTORS

BOARD-TO-BOARD HEADERS & RECEPTACLES



✓ Active

TE CONNECTIVITY (TE)
MOD II DBL ROW RECP ASSY
[AMPMODU](#) | [AMPMODU](#)

4-87964-1
TE Internal Number: 4-87964-1
Mil-Spec: M55302/128-CJ1C

[EU RoHS Compliant](#)
[EU ELV Compliant](#)
Connector Style Receptacle

Centerline (mm) 2.54

Sealable No

Centerline (Pitch) (in) .1

Number of Positions 84

[↓](#) **PRODUCT DRAWING**
English

[↓](#) **3D PDF**

DOCUMENTATION

Product Drawings

HOUSING ASSEMBLY, MOD II, DOUBLE ROW, IN LINE 2.54[.100]?22, SHORT POINT CONTACTS

PDF [\(TIFF AVAILABLE\)](#)

English

CAD Files

3D PDF

PDF

3D

Customer View Model

2D_DXF.ZIP

English

Customer View Model

3D_IGS.ZIP

English

Customer View Model

3D_STP.ZIP

English

FEATURES



Please review product documents or [contact us](#) for the latest agency approval information.

Please Note: Use the Product Drawing for all design activity.

Product Type Features

Connector Style Receptacle

Sealable No

Terminates To Printed Circuit Board

Series AMPMODU, MOD II

Row-to-Row Spacing 2.54 mm [.1 in]

PCB Mounting Orientation Right Angle

Connector Type Connector Assembly

Boss Without

Profile Standard

Product Type Connector

Configuration Features

Number of Positions 84

Number of Rows 2

Stackable No

Body Features

Keying Plug Number 102188-1

Contact Features

Contact Mating Area Plating Material Gold

Contact Mating Area Plating Thickness 1.27 µm [50 µin]

Solder Tail Contact Plating Thickness 1.27 µm [50 µin]

Contact Configuration Short Point

Contact Base Material Phosphor Bronze

Contact Type Socket

Solder Tail Contact Plating Material Gold Flash over Nickel

Termination Features

Termination Post Length 3.68 mm [.145 in]

Termination Method to PC Board Through Hole - Solder

Mechanical Attachment

PCB Mount Retention Without

Housing Features

Centerline (mm) 2.54
Centerline (Pitch) (in) .1
Housing Material Polyphenylene Sulfide (PPS)
Housing Entry Style Closed, Side
Housing Color Natural

Dimensions

Height 6.05 mm [.238 in]
Tail Length 3.68 mm [.145 in]
PCB Thickness (Recommended) 2.36 mm [.093 in]

Usage Conditions

High Temperature Compatible No

Operation/Application

Pick and Place Cover Without
Assembly Process Feature Board Standoff

Industry Standards

MIL-C-55032 Yes

Packaging Features

Packaging Method Package
Packaging Quantity 1

Statement of Compliance

Statement of Compliance
PDF